

MT9510 XP

Tri-Temp Pick-and-Place Handler



Automotive



Mobility



IoT/IoV & Optoelectronics



Computing & Network



Industrial & Medical



Consumer

Productivity

- Up to 5,300 UPH
- Up to x8 test site parallelism
- Fast index time 0.38 s
- High temperature accuracy
- Easy package style conversion in 15 mins
- Kitable system for QFP, BGA, PGA, QFN and other packages

Flexibility

- Device size from 3 mm x 3 mm to 70 mm x 70 mm
- Large and small size packages e.g. QFP, BGA, PGA and QFN
- Output versions: automatic tray module and single tray
- Advanced, scalable ESD protection
- Standard IC and MEMS/sensor test
- Contacting: standard; high frequency and Kelvin

- Full tri-temp range: -55°C to +175°C
- Temperature stability $\pm 0.5^{\circ}\text{C}$
- Temperature accuracy $\pm 2.0^{\circ}\text{C}$

- Small footprint
- Flat vertical contact site
- Large production-proven installed base

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Specifications

Platform

Performance Characteristics

- Throughput up to 5,300 UPH
- Index Time (virtual index time for multiple contact sites), octal mode: 0.05 s / device

Temperature Characteristics

- Ambient, ambient hot (+ 155°C standard, +175°C optional)
- Tri-temp (-55°C to +155°C, +175°C optional)
- Test Site Accuracy $\pm 2^{\circ}\text{C}$
- Test Site Temperature Stability $\pm 0.5^{\circ}\text{C}$

Loading/ Unloading

- All commonly used trays acc. to JEDEC standard CO-012, CO-029 and CO-034, others on request
- Type of Loader: tray stack, separate input/output tray loop
- Loading/Unloading Possible During Operation: Yes

Contacting

- Contact Modes
 - Parallel
 - Ping-pong
- Applications
 - Short contact ambient (plunge to board)
 - Short contact tri-temp (plunge to board)
 - Standard (including temperature insulation and hot air purge)

Bin Categories

- High volume plus 3 or 6 manual categories
- Software binning categories: 32

Docking

- Docking Height: 990 mm (floor to CUH center)
- All commonly used docking systems and test heads are supported

Available Versions

- Tray to tray

Available Options (selection)

- Interface SECS-II / GEM
- Automatic feet
- Ionizer, I/O area and contact chamber
- Charged plate monitor (CPM)
- Ground fault monitoring
- Double device detection
- DI-Core InSight
- 2D code reader
- Safe LN₂ tank change
- De-icing monitoring
- Color tray detection

Facility Requirements

- Power Supply
 - Factory setting: 400 V AC 3 phases/N/PE, 16 Amps each
 - Alternative connections: 208 V AC 3 phases/N/PE, 16 Amps each. 230 V AC 1 phase/N/PE, 32 Amps 50/60
- Power Consumption: all heaters on: max. 5,200 W
- LN₂ Consumption (for Cold Operation Only)
 - Typ. 18 l/h for cold operation
 - Typ. 33 l/h for cooling down from ambient to -55°C
- Compressed Air Pressure and Consumption
 - Nominal pressure: 5 to 10 bar (70 to 145 psi)
 - Consumption depends on temperature and operation mode: 170 l/min to 940 l/min
- Mobility: system is on casters, handler can be moved by one person

Physical Dimensions

- Width / Height: 1.19 m x 1.57 m (47" x 62")
- Weight: 850 kg (1,900 lbs). Including packing crate: 1,050 kg (2,350 lbs)

Standards

- CE
- SEMI S2-g3 assessment

Change Kit

Device Types

- Conversion Kits for QFP, BGA, μ BGA, PLCC, TSSOP, CSP, QFN (MLF/MLP), PGA, LGA, MCM, other package styles on request

Device Specifications

- 3 mm x 3 mm to 14 mm x 14 mm (for up to 8 contact sites)
- Min. lead/pad/ball pitch: 0.4 mm

Kit Changeover

- Uses conversion kits for easy package style conversion
- Required conversion time typ. 15 min for 1 person
- No adjustments required after package style conversion

Contactors

- Cohu offers contactors for all package versions and applications, i.e. standard, high frequency and Kelvin

Specifications subject to change without notice. For detailed performance specifications, please contact Cohu.